

# HD74LV1GT00A

## 2-input NAND Gate / CMOS Logic Level Shifter

REJ03D0115-0800Z (Previous ADE-205-325F (Z)) Rev.8.00 Sep.22.2003

#### **Description**

The HD74LV1GT00A is high-speed CMOS two input NAND gate using silicon gate CMOS process. With CMOS low power dissipation, it provides high-speed equivalent to LS-TTL series. The internal circuit of three stages construction with buffer provides wide noise margin and stable output. The input protection circuitry on this device allows over voltage tolerance on the input, allowing the device to be used as a logic-level translator from 3.0 V CMOS Logic to 5.0 V CMOS Logic or from 1.8 V CMOS logic to 3.0 V CMOS Logic while operating at the high-voltage power supply. Low voltage and high-speed operation is suitable for the battery powered products (e.g., notebook computers), and the low power consumption extends the battery life.

#### **Features**

- The basic gate function is lined up as Renesas uni logic series.
- Supplied on emboss taping for high-speed automatic mounting.
- TTL compatible input level.
  - Supply voltage range: 3.0 to 5.5 V

Operating temperature range: -40 to +85°C

• Logic-level translate function

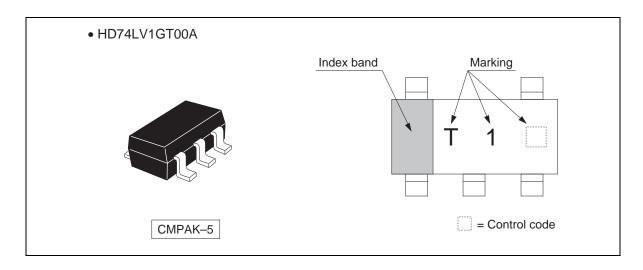
3.0 V CMOS logic  $\rightarrow$  5.0 V CMOS logic (@V<sub>CC</sub> = 5.0 V)

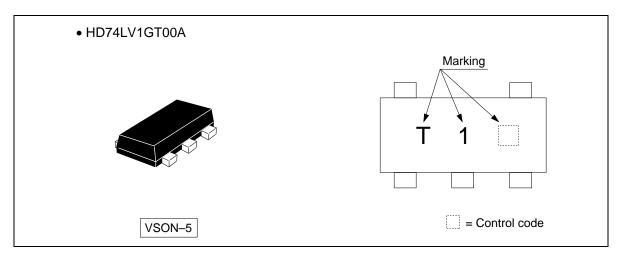
1.8 V or 2.5 V CMOS logic  $\rightarrow$  3.3 V CMOS logic (@V<sub>CC</sub> = 3.3 V)

- All inputs  $V_{IH}$  (Max.) = 5.5 V (@V<sub>CC</sub> = 0 V to 5.5 V) All outputs  $V_{O}$  (Max.) = 5.5 V (@V<sub>CC</sub> = 0 V)
- Output current  $\pm 6$  mA (@V<sub>CC</sub> = 3.0 V to 3.6 V),  $\pm 12$  mA (@V<sub>CC</sub> = 4.5 V to 5.5 V)
- All the logical input has hysteresis voltage for the slow transition.
- Ordering Information

Part Name	Package Type	Package Code	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LV1GT00ACME	CMPAK-5 pin	CMPAK-5V	CM	E (3,000 pcs/reel)
		CMPAK-5V(O)	_	
HD74LV1GT00AVSE	VSON-5 pin	TNP-5DV	VS	_

#### **Outline and Article Indication**



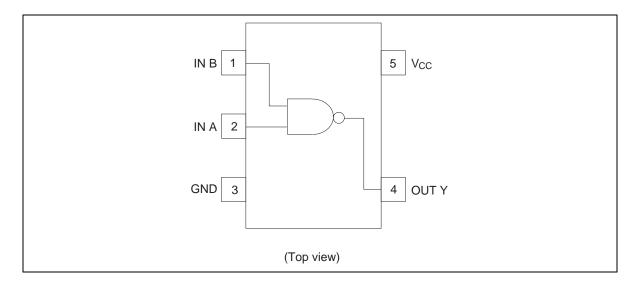


## **Function Table**

Inputs		Output Y	
A	В		
L	L	Н	
L	Н	Н	
Н	L	Н	
Н	Н	L	

H : High level L : Low level

## **Pin Arrangement**



#### **Absolute Maximum Ratings**

Item	Symbol	Ratings	Unit	Test Conditions
Supply voltage range	V <sub>CC</sub>	-0.5 to 7.0	V	
Input voltage range *1	VI	-0.5 to 7.0	V	
Output voltage range *1, 2	Vo	$-0.5$ to $V_{CC} + 0.5$	V	Output : H or L
		-0.5 to 7.0	<del></del>	V <sub>CC</sub> : OFF
Input clamp current	I <sub>IK</sub>	-20	mA	V <sub>I</sub> < 0
Output clamp current	I <sub>OK</sub>	±50	mA	$V_0 < 0$ or $V_0 > V_{CC}$
Continuous output current	Io	±25	mA	$V_{O} = 0$ to $V_{CC}$
Continuous current through V <sub>CC</sub> or GND	I <sub>CC</sub> or I <sub>GND</sub>	±50	mA	
Maximum power dissipation at Ta = 25°C (in still air) *3	P <sub>T</sub>	200	mW	
Storage temperature	Tstg	-65 to 150	°C	

Notes: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore no two of which may be realized at the same time.

- 1. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- 2. This value is limited to 5.5 V maximum.
- 3. The maximum package power dissipation was calculated using a junction temperature of 150°C.

#### **Recommended Operating Conditions**

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage range	V <sub>CC</sub>	3.0	5.5	V	
Input voltage range	VI	0	5.5	V	
Output voltage range	Vo	0	V <sub>CC</sub>	V	
Output current	I <sub>OL</sub>	_	6	mA	V <sub>CC</sub> = 3.0 to 3.6 V
		_	12		$V_{CC} = 4.5 \text{ to } 5.5 \text{ V}$
	I <sub>OH</sub>	_	-6		$V_{CC} = 3.0 \text{ to } 3.6 \text{ V}$
		_	-12		$V_{CC} = 4.5 \text{ to } 5.5 \text{ V}$
Input transition rise or fall rate	Δt / Δν	0	100	ns / V	$V_{CC} = 3.0 \text{ to } 3.6 \text{ V}$
		0	20		$V_{CC} = 4.5 \text{ to } 5.5 \text{ V}$
Operating free-air temperature	Ta	-40	85	°C	

Note: Unused or floating inputs must be held high or low.

#### **Electrical Characteristic**

•  $Ta = -40 \text{ to } 85^{\circ}\text{C}$ 

Item	Symbol	V <sub>CC</sub> (V) *	Min	Тур	Max	Unit	Test condition
Input voltage	V <sub>IH</sub>	3.0 to 3.6	1.5	_	_	V	
		4.5 to 5.5	2.0	_	_		
	V <sub>IL</sub>	3.0 to 3.6	_	_	0.6		
		4.5 to 5.5	_	_	0.8	_	
Hysteresis voltage	V <sub>H</sub>	3.3	_	0.10	_	V	$V_T^+ - V_T^-$
		5.0	_	0.15	_	_	
Output voltage	V <sub>OH</sub>	Min to Max	V <sub>CC</sub> -0.1	_	_	V	$I_{OH} = -50 \ \mu A$
		3.0	2.48	_	_		$I_{OH} = -6 \text{ mA}$
		4.5	3.8	_	_		I <sub>OH</sub> = -12 mA
	V <sub>OL</sub>	Min to Max	_	_	0.1	_	$I_{OL} = 50 \mu\text{A}$
		3.0	_	_	0.44		I <sub>OL</sub> = 6 mA
		4.5	_	_	0.55		I <sub>OL</sub> = 12 mA
Input current	I <sub>IN</sub>	0 to 5.5	_	_	±1	μΑ	V <sub>IN</sub> = 5.5 V or GND
Quiescent supply current	Icc	5.5	_	_	10	μΑ	$V_{IN} = V_{CC}$ or GND, $I_O = 0$
	$\Delta I_{CC}$	5.5	_	_	1.5	mA	One input $V_{IN} = 3.4 \text{ V}$ , other input $V_{CC}$ or GND
Output leakage current	I <sub>OFF</sub>	0	_	_	5	μΑ	$V_{IN}$ or $V_O = 0$ to 5.5 V
Input capacitance	C <sub>IN</sub>	5.0	_	2.5	_	pF	$V_{IN} = V_{CC}$ or GND

Note: For conditions shown as Min or Max, use the appropriate values under recommended operating conditions.

## **Switching Characteristics**

 $\bullet \quad V_{CC} = 3.3 \pm 0.3 \ V$ 

Item	Symbol	Ta = :	25°C	Ta = -40 to 85°C		Unit		FROM	то	
		Min	Тур	Max	Min	Max	_	Conditions	(Input)	(Output)
Propagation	t <sub>PLH</sub>	_	7.0	10.0	1.0	12.0	ns	C <sub>L</sub> = 15 pF	A or B	Υ
delay time	t <sub>PHL</sub>	_	7.5	12.0	1.0	14.0	_	C <sub>L</sub> = 50 pF	_	

 $\bullet \quad V_{CC} = 5.0 \pm 0.5 \ V$ 

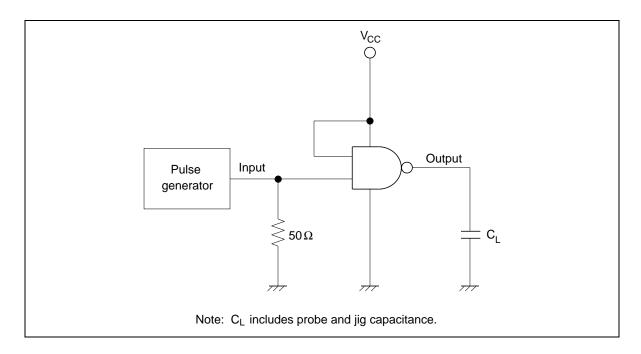
Item	Symbol	Ta = 2	25°C	C Ta = -40 to 85°C		Unit		FROM	ТО	
		Min	Тур	Max	Min	Max	_	Conditions	(Input)	(Output)
Propagation	t <sub>PLH</sub>	_	5.0	6.9	1.0	8.0	ns	C <sub>L</sub> = 15 pF	A or B	Υ
delay time	t <sub>PHL</sub>	_	5.5	7.9	1.0	9.0		C <sub>L</sub> = 50 pF	-	

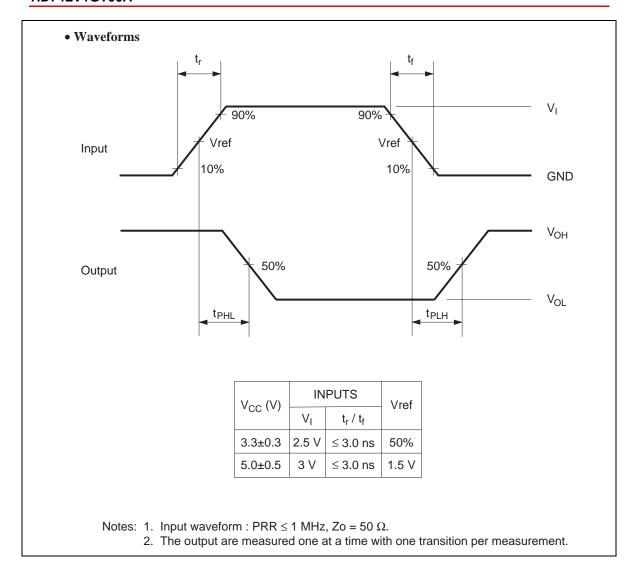
## **Operating Characteristics**

•  $C_L = 50 pF$ 

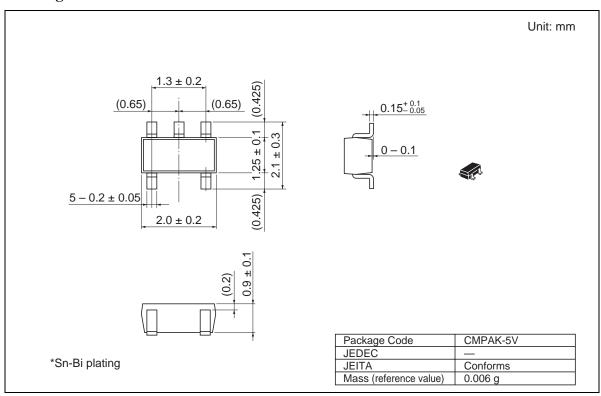
Item	Symbol	V <sub>CC</sub> (V)	Ta = 25°C		Unit	<b>Test Conditions</b>	
			Min	Тур	Max	_	
Power dissipation capacitance	$C_{PD}$	5.0	_	11.0	_	pF	f = 10 MHz

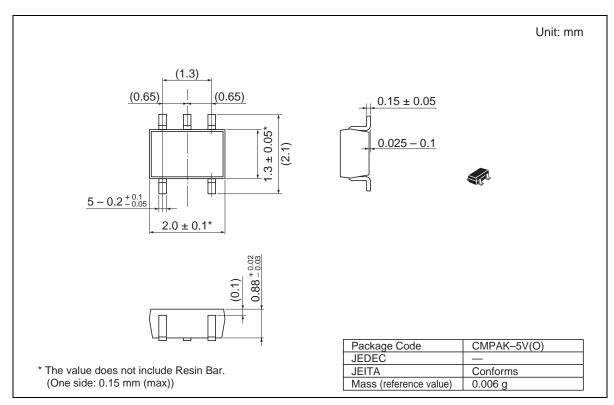
## **Test Circuit**

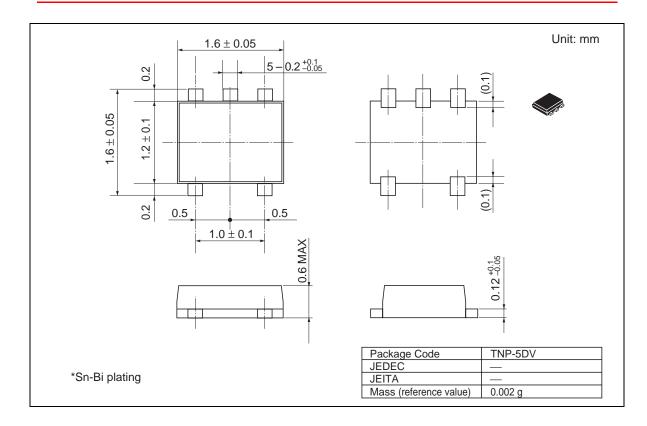




## **Package Dimensions**







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